

74AHC1G00-Q100; 74AHCT1G00-Q100

2-input NAND gate

Rev. 1 — 16 September 2013

Product data sheet

1. General description

74AHC1G00-Q100 and 74AHCT1G00-Q100 are high-speed Si-gate CMOS devices. They provide a 2-input NAND function.

The AHC device has CMOS input switching levels and supply voltage range 2 V to 5.5 V.

The AHCT device has TTL input switching levels and supply voltage range 4.5 V to 5.5 V.

This product has been qualified to the Automotive Electronics Council (AEC) standard Q100 (Grade 1) and is suitable for use in automotive applications.

2. Features and benefits

- Automotive product qualification in accordance with AEC-Q100 (Grade 1)
 - ◆ Specified from -40°C to $+85^{\circ}\text{C}$ and from -40°C to $+125^{\circ}\text{C}$
- Symmetrical output impedance
- High noise immunity
- Low power dissipation
- Balanced propagation delays
- SOT353-1 and SOT753 package options
- ESD protection:
 - ◆ MIL-STD-883, method 3015 exceeds 2000 V
 - ◆ HBM JESD22-A114F exceeds 2000 V
 - ◆ MM JESD22-A115-A exceeds 200 V ($C = 200\text{ pf}$, $R = 0\ \Omega$)

3. Ordering information

Table 1. Ordering information

| Type number | Package | | | |
|---------------------------------------|---|--------|---|----------|
| | Temperature range | Name | Description | Version |
| 74AHC1G00GW-Q100 74AHCT1G00GW-Q100 | -40°C to $+125^{\circ}\text{C}$ | TSSOP5 | plastic thin shrink small outline package; 5 leads; body width 1.25 mm | SOT353-1 |
| 74AHC1G00GV-Q100 74AHCT1G00GV-Q100 | -40°C to $+125^{\circ}\text{C}$ | SC-74A | plastic surface-mounted package; 5 leads | SOT753 |



4. Marking

Table 2. Marking codes

| Type number | Marking |
|-------------------|---------|
| 74AHC1G00GW-Q100 | AA |
| 74AHCT1G00GW-Q100 | A00 |
| 74AHC1G00GV-Q100 | CA |
| 74AHCT1G00GV-Q100 | C00 |

5. Functional diagram

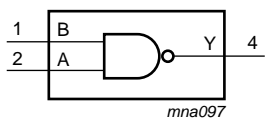


Fig 1. Logic symbol

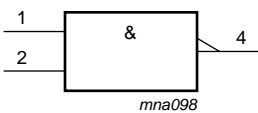


Fig 2. IEC logic symbol

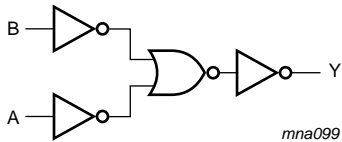


Fig 3. Logic diagram

6. Pinning information

6.1 Pinning

74AHC1G00-Q100
74AHCT1G00-Q100

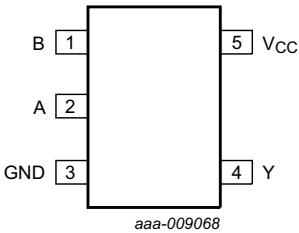


Fig 4. Pin configuration

6.2 Pin description

Table 3. Pin description

| Symbol | Pin | Description |
|-----------------|-----|----------------|
| B | 1 | data input |
| A | 2 | data input |
| GND | 3 | ground (0 V) |
| Y | 4 | data output |
| V _{CC} | 5 | supply voltage |

7. Functional description

Table 4. Function table

H = HIGH voltage level; L = LOW voltage level

| Inputs | | Output |
|--------|---|--------|
| A | B | Y |
| L | L | H |
| L | H | H |
| H | L | H |
| H | H | L |

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol | Parameter | Conditions | Min | Max | Unit |
|-----------|-------------------------|--|-------|------|------|
| V_{CC} | supply voltage | | -0.5 | +7.0 | V |
| V_I | input voltage | | -0.5 | +7.0 | V |
| I_{IK} | input clamping current | $V_I < -0.5$ V | -20 | - | mA |
| I_{OK} | output clamping current | $V_O < -0.5$ V or $V_O > V_{CC} + 0.5$ V | [1] - | ±20 | mA |
| I_O | output current | -0.5 V < V_O < $V_{CC} + 0.5$ V | - | ±25 | mA |
| I_{CC} | supply current | | - | 75 | mA |
| I_{GND} | ground current | | -75 | - | mA |
| T_{stg} | storage temperature | | -65 | +150 | °C |
| P_{tot} | total power dissipation | $T_{amb} = -40$ °C to +125 °C | [2] - | 250 | mW |

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] For both TSSOP5 and SC-74A packages: above 87.5 °C the value of P_{tot} derates linearly with 4.0 mW/K.

9. Recommended operating conditions

Table 6. Recommended operating conditions

Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 74AHC1G00-Q100 | | | 74AHCT1G00-Q100 | | | Unit |
|---------------------|-------------------------------------|--------------------------|----------------|-----|----------|-----------------|-----|----------|------|
| | | | Min | Typ | Max | Min | Typ | Max | |
| V_{CC} | supply voltage | | 2.0 | 5.0 | 5.5 | 4.5 | 5.0 | 5.5 | V |
| V_I | input voltage | | 0 | - | 5.5 | 0 | - | 5.5 | V |
| V_O | output voltage | | 0 | - | V_{CC} | 0 | - | V_{CC} | V |
| T_{amb} | ambient temperature | | -40 | +25 | +125 | -40 | +25 | +125 | °C |
| $\Delta t/\Delta V$ | input transition rise and fall rate | $V_{CC} = 3.3$ V ± 0.3 V | - | - | 100 | - | - | - | ns/V |
| | | $V_{CC} = 5.0$ V ± 0.5 V | - | - | 20 | - | - | 20 | ns/V |

10. Static characteristics

Table 7. Static characteristics

Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 25 °C | | | –40 °C to +85 °C | | –40 °C to +125 °C | | Unit |
|--------------------------|---------------------------|--|-------|-----|------|------------------|------|-------------------|------|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| For type 74AHC1G00-Q100 | | | | | | | | | | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 2.0 V | 1.5 | - | - | 1.5 | - | 1.5 | - | V |
| | | V _{CC} = 3.0 V | 2.1 | - | - | 2.1 | - | 2.1 | - | V |
| | | V _{CC} = 5.5 V | 3.85 | - | - | 3.85 | - | 3.85 | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 2.0 V | - | - | 0.5 | - | 0.5 | - | 0.5 | V |
| | | V _{CC} = 3.0 V | - | - | 0.9 | - | 0.9 | - | 0.9 | V |
| | | V _{CC} = 5.5 V | - | - | 1.65 | - | 1.65 | - | 1.65 | V |
| V _{OH} | HIGH-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | | | |
| | | I _O = –50 μA; V _{CC} = 2.0 V | 1.9 | 2.0 | - | 1.9 | - | 1.9 | - | V |
| | | I _O = –50 μA; V _{CC} = 3.0 V | 2.9 | 3.0 | - | 2.9 | - | 2.9 | - | V |
| | | I _O = –50 μA; V _{CC} = 4.5 V | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | I _O = –4.0 mA; V _{CC} = 3.0 V | 2.58 | - | - | 2.48 | - | 2.40 | - | V |
| | | I _O = –8.0 mA; V _{CC} = 4.5 V | 3.94 | - | - | 3.8 | - | 3.70 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} | | | | | | | | |
| | | I _O = 50 μA; V _{CC} = 2.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 50 μA; V _{CC} = 3.0 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 50 μA; V _{CC} = 4.5 V | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 4.0 mA; V _{CC} = 3.0 V | - | - | 0.36 | - | 0.44 | - | 0.55 | V |
| | | I _O = 8.0 mA; V _{CC} = 4.5 V | - | - | 0.36 | - | 0.44 | - | 0.55 | V |
| I _I | input leakage current | V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V | - | - | 0.1 | - | 1.0 | - | 2.0 | μA |
| I _{CC} | supply current | V _I = V _{CC} or GND; I _O = 0 A; V _{CC} = 5.5 V | - | - | 1.0 | - | 10 | - | 40 | μA |
| C _I | input capacitance | | - | 1.5 | 10 | - | 10 | - | 10 | pF |
| For type 74AHCT1G00-Q100 | | | | | | | | | | |
| V _{IH} | HIGH-level input voltage | V _{CC} = 4.5 V to 5.5 V | 2.0 | - | - | 2.0 | - | 2.0 | - | V |
| V _{IL} | LOW-level input voltage | V _{CC} = 4.5 V to 5.5 V | - | - | 0.8 | - | 0.8 | - | 0.8 | V |
| V _{OH} | HIGH-level output voltage | V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V | | | | | | | | |
| | | I _O = –50 μA | 4.4 | 4.5 | - | 4.4 | - | 4.4 | - | V |
| | | I _O = –8.0 mA | 3.94 | - | - | 3.8 | - | 3.70 | - | V |
| V _{OL} | LOW-level output voltage | V _I = V _{IH} or V _{IL} ; V _{CC} = 4.5 V | | | | | | | | |
| | | I _O = 50 μA | - | 0 | 0.1 | - | 0.1 | - | 0.1 | V |
| | | I _O = 8.0 mA | - | - | 0.36 | - | 0.44 | - | 0.55 | V |
| I _I | input leakage current | V _I = 5.5 V or GND; V _{CC} = 0 V to 5.5 V | - | - | 0.1 | - | 1.0 | - | 2.0 | μA |

Table 7. Static characteristics ...continued
 Voltages are referenced to GND (ground = 0 V).

| Symbol | Parameter | Conditions | 25 °C | | | –40 °C to +85 °C | | –40 °C to +125 °C | | Unit |
|-----------------|---------------------------|--|-------|-----|------|------------------|-----|-------------------|-----|---------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |
| I_{CC} | supply current | $V_I = V_{CC}$ or GND; $I_O = 0$ A; $V_{CC} = 5.5$ V | - | - | 1.0 | - | 10 | - | 40 | μ A |
| ΔI_{CC} | additional supply current | per input pin; $V_I = 3.4$ V; other inputs at V_{CC} or GND; $I_O = 0$ A; $V_{CC} = 5.5$ V | - | - | 1.35 | - | 1.5 | - | 1.5 | mA |
| C_I | input capacitance | | - | 1.5 | 10 | - | 10 | - | 10 | pF |

11. Dynamic characteristics

Table 8. Dynamic characteristics
 GND = 0 V; $t_r = t_f \leq 3.0$ ns. For test circuit, see [Figure 6](#).

| Symbol | Parameter | Conditions | 25 °C | | | –40 °C to +85 °C | | –40 °C to +125 °C | | Unit |
|--------|-----------|------------|-------|-----|-----|------------------|-----|-------------------|-----|------|
| | | | Min | Typ | Max | Min | Max | Min | Max | |

For type 74AHC1G00-Q100

| | | | | | | | | | | |
|----------|-------------------------------|--|---|-----|------|-----|------|-----|------|----|
| t_{pd} | propagation delay | A and B to Y; see Figure 5 [1] | | | | | | | | |
| | | $V_{CC} = 3.0$ V to 3.6 V [2] | | | | | | | | |
| | | $C_L = 15$ pF | - | 4.5 | 7.9 | 1.0 | 9.5 | 1.0 | 10.5 | ns |
| | | $C_L = 50$ pF | - | 6.5 | 11.4 | 1.0 | 13.0 | 1.0 | 14.5 | ns |
| | | $V_{CC} = 4.5$ V to 5.5 V [3] | | | | | | | | |
| | | $C_L = 15$ pF | - | 3.5 | 5.5 | 1.0 | 6.5 | 1.0 | 7.0 | ns |
| C_{PD} | power dissipation capacitance | $C_L = 50$ pF | - | 4.9 | 7.5 | 1.0 | 8.5 | 1.0 | 9.5 | ns |
| | | per buffer; $C_L = 50$ pF; $f = 1$ MHz; $V_I =$ GND to V_{CC} [4] | - | 17 | - | - | - | - | - | pF |

For type 74AHCT1G00-Q100

| | | | | | | | | | | |
|----------|-------------------------------|---|---|-----|-----|-----|-----|-----|------|----|
| t_{pd} | propagation delay | A and B to Y; see Figure 5 ; [1] $V_{CC} = 4.5$ V to 5.5 V [3] | | | | | | | | |
| | | $C_L = 15$ pF | - | 3.6 | 6.2 | 1.0 | 7.1 | 1.0 | 8.0 | ns |
| | | $C_L = 50$ pF | - | 5.0 | 7.9 | 1.0 | 9.0 | 1.0 | 10.0 | ns |
| C_{PD} | power dissipation capacitance | per buffer; $V_I =$ GND to V_{CC} [4] | - | 18 | - | - | - | - | - | pF |

[1] t_{pd} is the same as t_{PLH} and t_{PHL} .

[2] Typical values are measured at $V_{CC} = 3.3$ V.

[3] Typical values are measured at $V_{CC} = 5.0$ V.

[4] C_{PD} is used to determine the dynamic power dissipation P_D (μ W).

$P_D = C_{PD} \times V_{CC}^2 \times f_i + \sum (C_L \times V_{CC}^2 \times f_o)$ where:

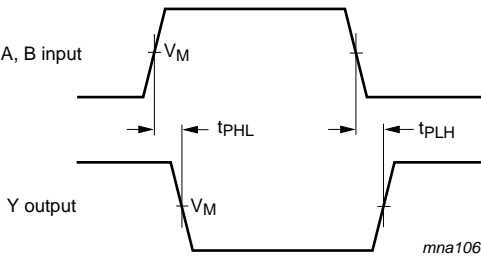
f_i = input frequency in MHz;

f_o = output frequency in MHz;

C_L = output load capacitance in pF;

V_{CC} = supply voltage in Volts.

12. Waveforms

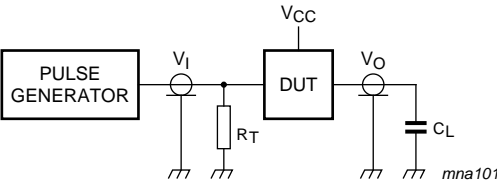


Measurement points are given in [Table 9](#).

Fig 5. The inputs (A and B) to output (Y) propagation delays

Table 9. Measurement point

| Type | Input | | Output |
|-----------------|-----------------|---------------------|---------------------|
| | V_I | V_M | V_M |
| 74AHC1G00-Q100 | GND to V_{CC} | $0.5 \times V_{CC}$ | $0.5 \times V_{CC}$ |
| 74AHCT1G00-Q100 | GND to 3.0 V | 1.5 V | $0.5 \times V_{CC}$ |



Test data is given in [Table 8](#). Definitions for test circuit:
 C_L = Load capacitance including jig and probe capacitance.
 R_T = Termination resistance should be equal to output impedance Z_o of the pulse generator.

Fig 6. Test circuit for measuring switching times

13. Package outline

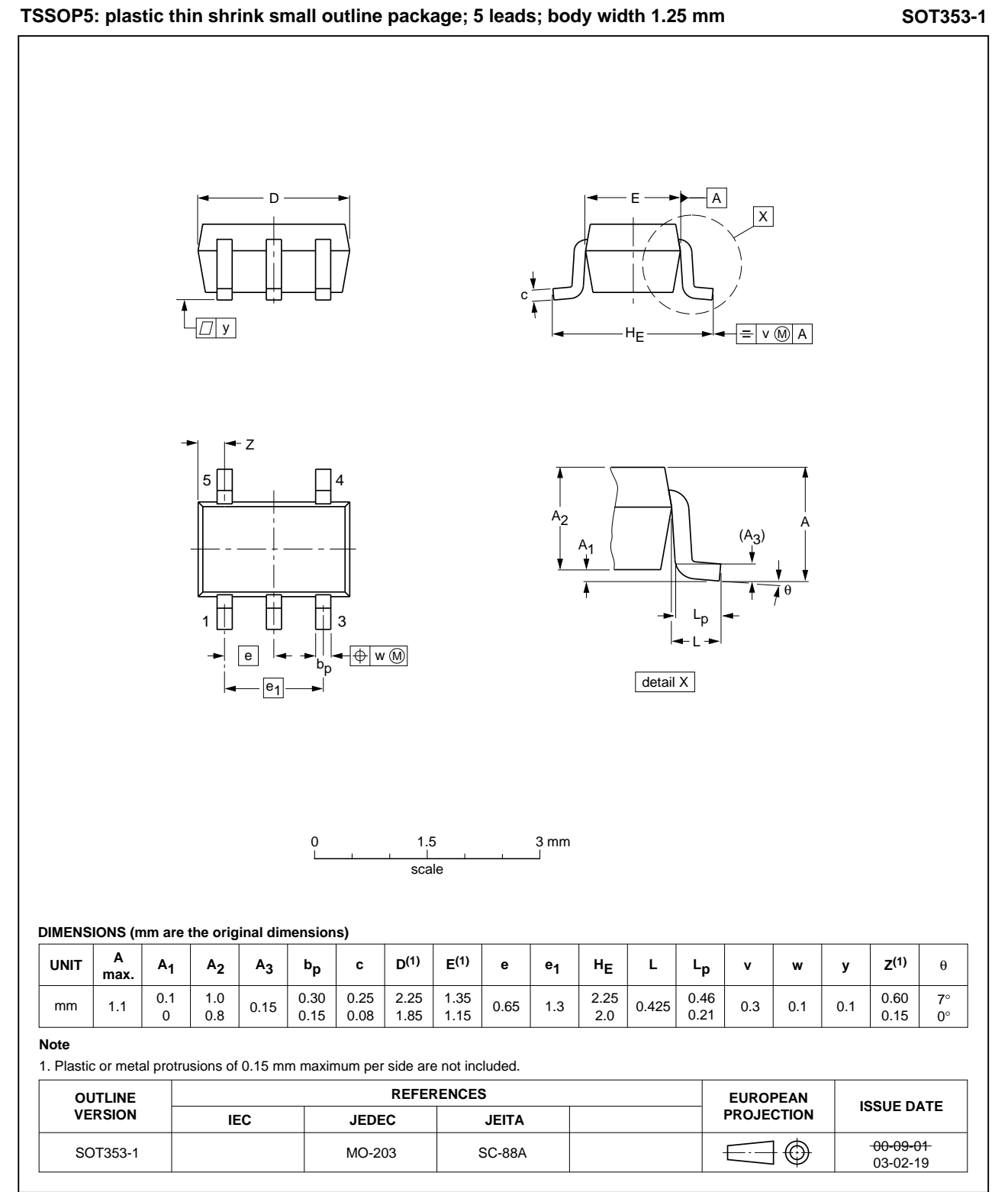


Fig 7. Package outline SOT353-1 (TSSOP5)

Plastic surface-mounted package; 5 leads

SOT753

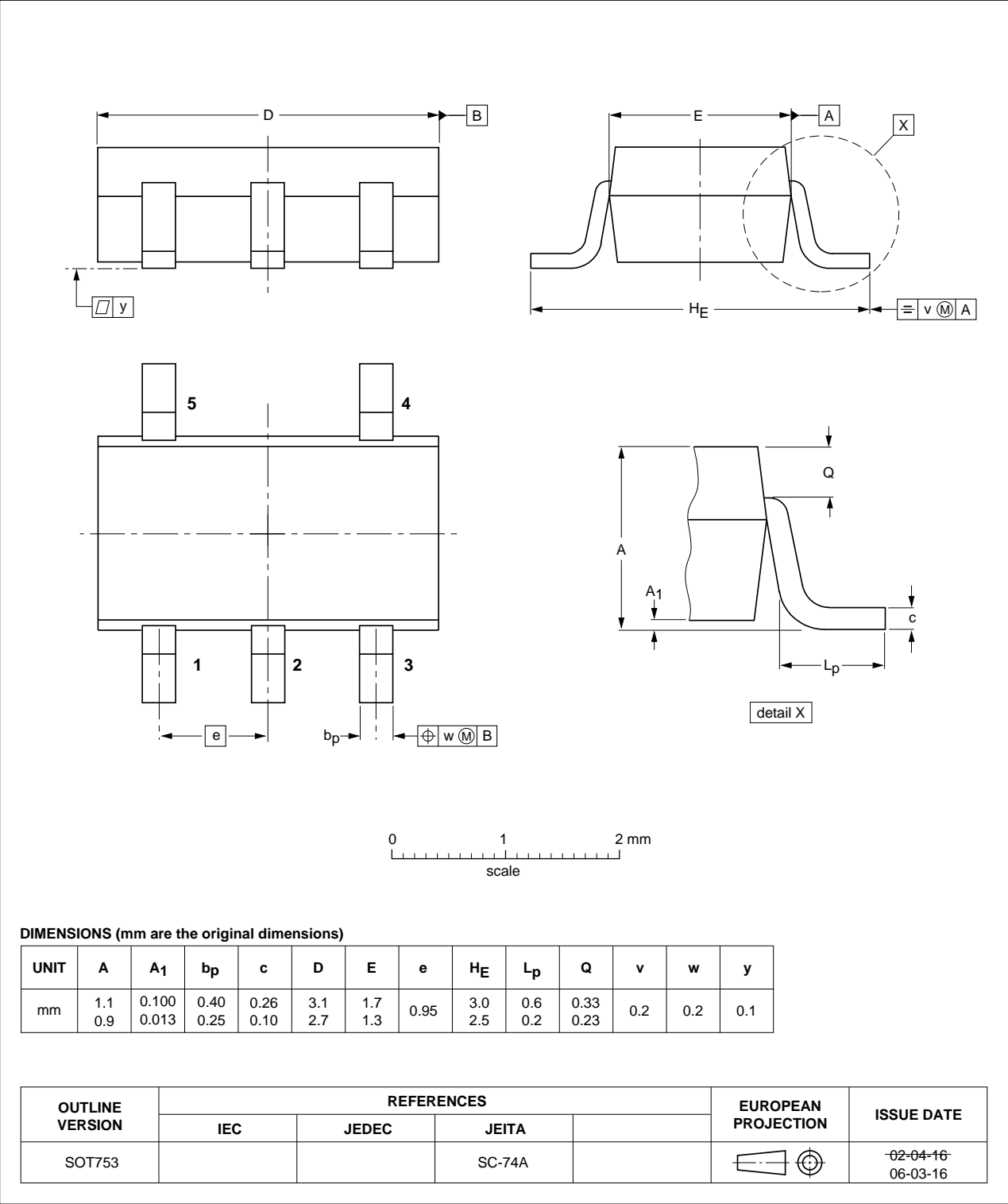


Fig 8. Package outline SOT753 (SC-74A)

14. Abbreviations

Table 10. Abbreviations

| Acronym | Description |
|---------|-----------------------------|
| CDM | Charged Device Model |
| DUT | Device Under Test |
| ESD | ElectroStatic Discharge |
| HBM | Human Body Model |
| MM | Machine Model |
| TTL | Transistor-Transistor Logic |

15. Revision history

Table 11. Revision history

| Document ID | Release date | Data sheet status | Change notice | Supersedes |
|-------------------------|--------------|--------------------|---------------|------------|
| 74AHC_AHCT1G00_Q100 v.1 | 20130916 | Product data sheet | - | - |

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16.1 Data sheet status

| Document status ^{[1][2]} | Product status ^[3] | Definition |
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